

Patent Abstracts of Japan

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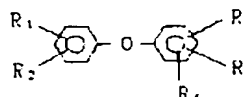
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TITLE : DEVELOPER COMPOSITION FOR RESIST



... ( I )

ABSTRACT : PURPOSE: To form a satisfactory resist pattern free from a residual thin film and scum especially at the fine part by adding at least one kind of specified anionic surfactant to a developer for a resist by 500-50,000ppm.

CONSTITUTION: At least one kind of anionic surfactant represented by formula I is added to a metal ion-free developer for a resist contg. org. base as the principal ingredient by 500-50,000ppm. In, formula I, at least one of R<sub>1</sub> and R<sub>2</sub> is 5-18C alkyl or alkoxy, the remainder is H, 5-18C alkyl or alkoxy, at least one of R<sub>3</sub>-R<sub>5</sub> is ammonium sulfonate or sulfonic acid substd. ammonium and the remainders are H, ammonium sulfonate or sulfonic acid substd. ammonium. When the resulting developer compsn. is used, a satisfactory pattern free from a residual thin film and scum can be formed.

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